



STW10NC60 STH10NC60FI

N-CHANNEL 600V - 0.6Ω - 10A - TO-247/ISOWATT218

PowerMesh™II MOSFET

| TYPE | V _{DSS} | R _{DS(on)} | I _D |
|-------------|------------------|---------------------|----------------|
| STW10NC60 | 600 V | < 0.75 Ω | 10 A |
| STH10NC60FI | 600 V | < 0.75 Ω | 10 A (*) |

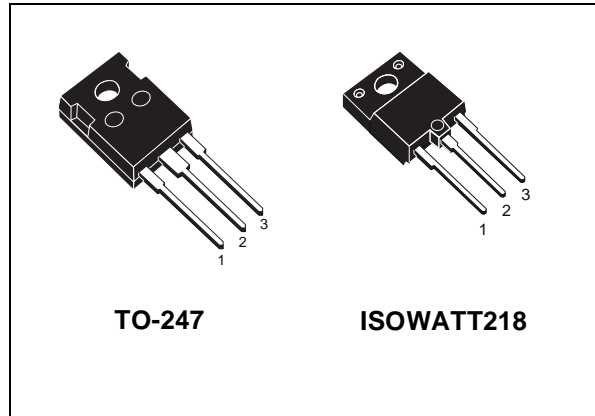
- TYPICAL R_{DS(on)} = 0.6 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- NEW HIGH VOLTAGE BENCHMARK
- GATE CHARGE MINIMIZED

DESCRIPTION

The PowerMESH™II is the evolution of the first generation of MESH OVERLAY™. The layout refinements introduced greatly improve the Ron*area figure of merit while keeping the device at the leading edge for what concerns switching speed, gate charge and ruggedness.

APPLICATIONS

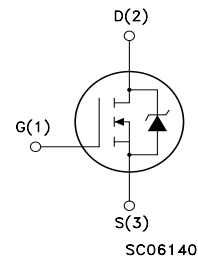
- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVER



TO-247

ISOWATT218

INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | | Unit |
|---------------------|--|-------------|-------------|------|
| | | STW10NC60 | STH10NC60FI | |
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 600 | | V |
| V _{DGR} | Drain-gate Voltage (R _{GS} = 20 kΩ) | 600 | | V |
| V _{GS} | Gate- source Voltage | ±30 | | V |
| I _D | Drain Current (continuous) at T _C = 25°C | 10 | 10 (*) | A |
| I _D | Drain Current (continuous) at T _C = 100°C | 6.3 | 6.3 (*) | A |
| I _{DM} (1) | Drain Current (pulsed) | 40 | 40 (*) | A |
| P _{TOT} | Total Dissipation at T _C = 25°C | 160 | 60 | W |
| | Derating Factor | 1.28 | 0.48 | W/°C |
| dv/dt | Peak Diode Recovery voltage slope | 3.5 | | V/ns |
| V _{ISO} | Insulation Withstand Voltage (DC) | - | 2500 | V |
| T _{stg} | Storage Temperature | - 55 to 150 | | °C |
| T _j | Max. Operating Junction Temperature | | | |

(*) Pulse width limited by safe operating area

(1) I_{SD} ≤ 10A, di/dt ≤ 100A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}

(*) Limited only by Maximum Temperature Allowed

STW10NC60 / STH10NC60FI

THERMAL DATA

| | | TO-247 | ISOWATT218 | |
|----------------|--|--------|------------|------|
| Rthj-case | Thermal Resistance Junction-case Max | 0.78 | 2.08 | °C/W |
| Rthj-amb | Thermal Resistance Junction-ambient Max | 30 | | °C/W |
| T _l | Maximum Lead Temperature For Soldering Purpose | 300 | | °C |

AVALANCHE CHARACTERISTICS

| Symbol | Parameter | Max Value | Unit |
|-----------------|--|-----------|------|
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max) | 10 | A |
| E _{AS} | Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 50 V) | 820 | mJ |

ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---|---|------|------|---------|----------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | I _D = 250 μA, V _{GS} = 0 | 600 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V _{DS} = Max Rating V _{DS} = Max Rating, T _C = 125 °C | | | 1 50 | μA μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | V _{GS} = ±30V | | | ±100 | nA |

ON (1)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250μA | 2 | 3 | 4 | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 10V, I _D = 4.5 A | | 0.6 | 0.75 | Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|---|------|------|------|------|
| g _{fs} (1) | Forward Transconductance | V _{DS} = 20 V, I _D = 4.5A | | 9 | | S |
| C _{iss} | Input Capacitance | V _{DS} = 25V, f = 1 MHz, V _{GS} = 0 | | 1420 | | pF |
| C _{OSS} | Output Capacitance | | | 205 | | pF |
| C _{rSS} | Reverse Transfer Capacitance | | | 35 | | pF |

ELECTRICAL CHARACTERISTICS (CONTINUED)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------|--------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD} = 300V, I_D = 4.5 A$ $R_G = 4.7\Omega, V_{GS} = 10V$ | | 20 | | ns |
| t_r | Rise Time | (see test circuit, Figure 3) | | 16 | | ns |
| Q_g | Total Gate Charge | $V_{DD} = 480V, I_D = 9.0 A,$ $V_{GS} = 10V$ | | 55 | 77 | nC |
| Q_{gs} | Gate-Source Charge | | | 4.5 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 31 | | nC |

SWITCHING OFF

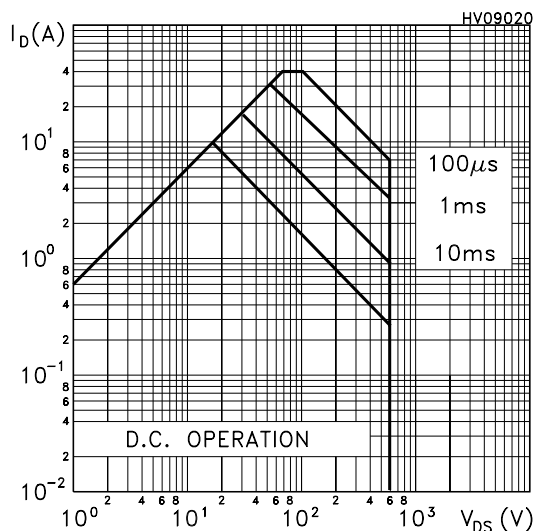
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------|---|------|------|------|------|
| $t_{d(off)}$ | Turn-off Delay Time | $V_{DD} = 300 V, I_D = 4.5 A$ $R_G = 4.7\Omega, V_{GS} = 10 V$ | | 64 | | ns |
| t_f | Fall Time | (Resistive Load see, Figure 3) | | 32 | | ns |
| $t_{r(Voff)}$ | Off-voltage Rise Time | $V_{DD} = 480V, I_D = 9.0 A,$ $R_G = 4.7\Omega, V_{GS} = 10V$ | | 19 | | ns |
| t_f | Fall Time | (Inductive Load see, Figure 5) | | 13 | | ns |
| t_c | Cross-over Time | | | 32 | | ns |

SOURCE DRAIN DIODE

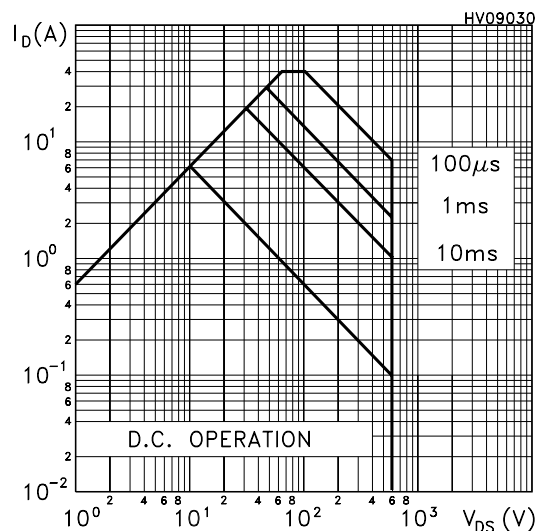
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|-------------------------------|---|------|------|------|---------|
| I_{SD} | Source-drain Current | | | | 10 | A |
| $I_{SDM} (2)$ | Source-drain Current (pulsed) | | | | 40 | A |
| $V_{SD} (1)$ | Forward On Voltage | $I_{SD} = 9 A, V_{GS} = 0$ | | | 1.6 | V |
| t_{rr} | Reverse Recovery Time | $I_{SD} = 9 A, di/dt = 100A/\mu s,$ $V_{DD} = 100V, T_j = 150^\circ C$ | | 600 | | ns |
| Q_{rr} | Reverse Recovery Charge | (see test circuit, Figure 5) | | 4.7 | | μC |
| I_{RRM} | Reverse Recovery Current | | | 15.5 | | A |

Note: 1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.
2. Pulse width limited by safe operating area.

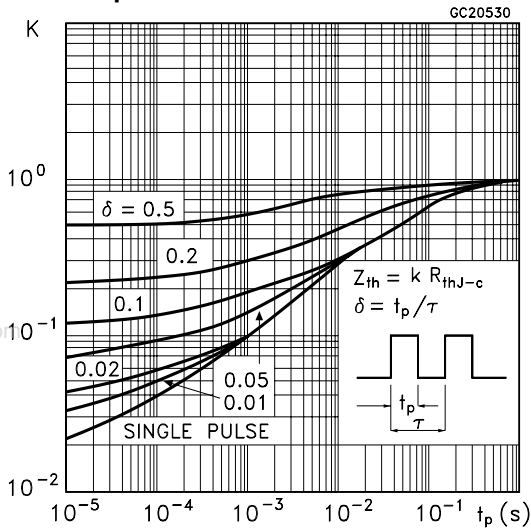
Safe Operating Area for TO-247



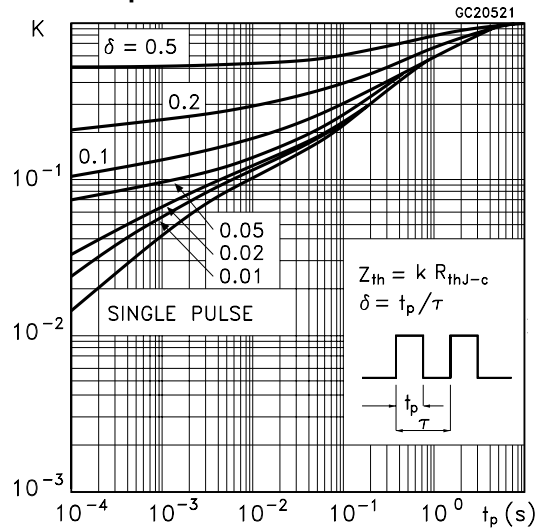
Safe Operating Area for ISOWATT218



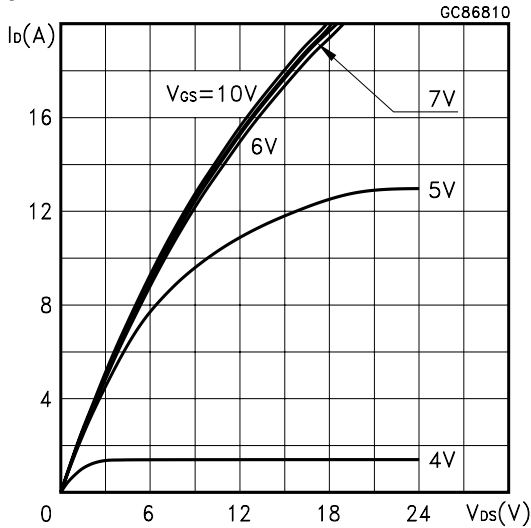
Thermal Impedance for TO-247



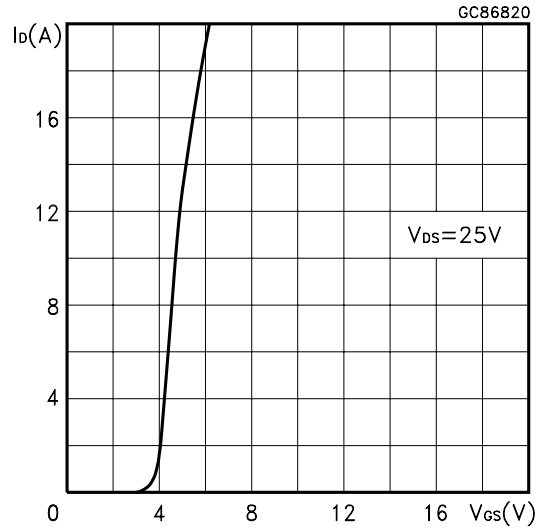
Thermal Impedance for ISOWATT218



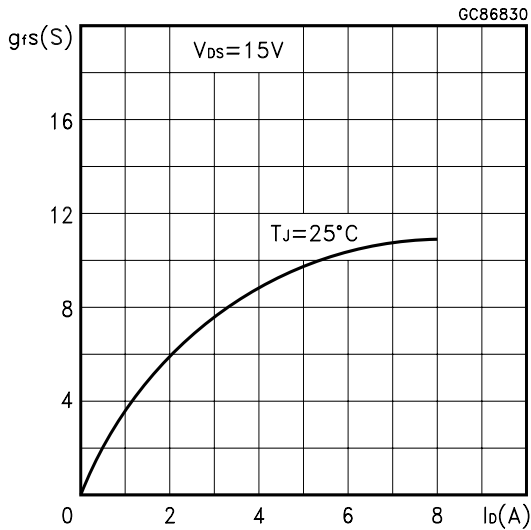
Output Characteristics



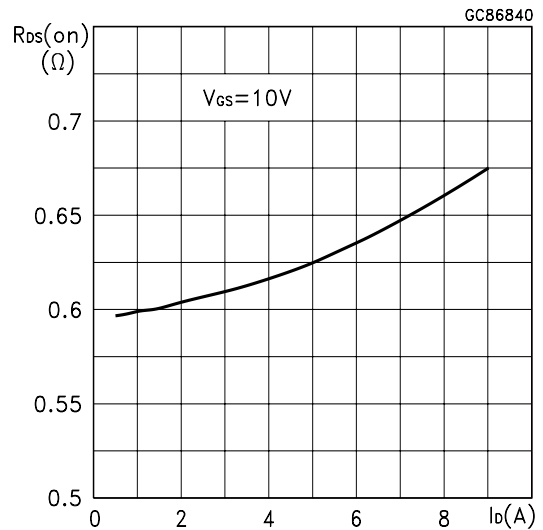
Transfer Characteristics



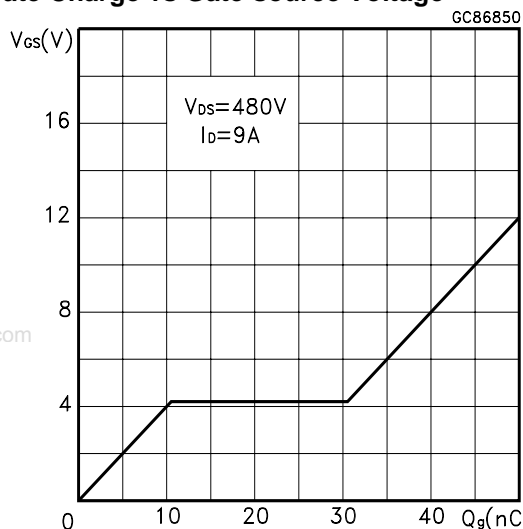
Transconductance



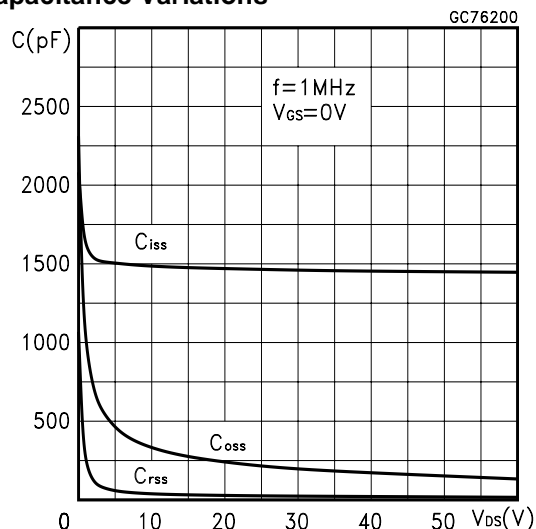
Static Drain-source On Resistance



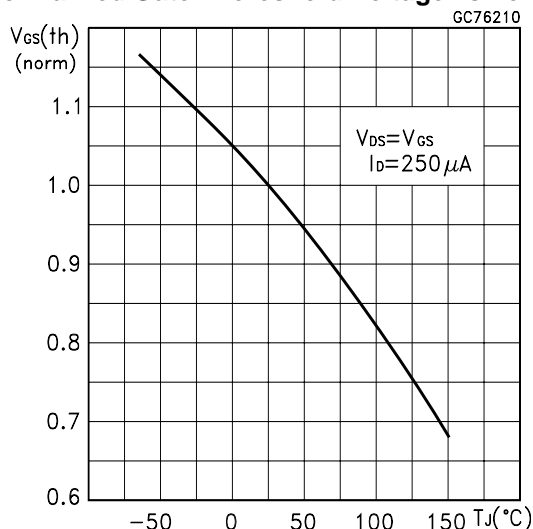
Gate Charge vs Gate-source Voltage



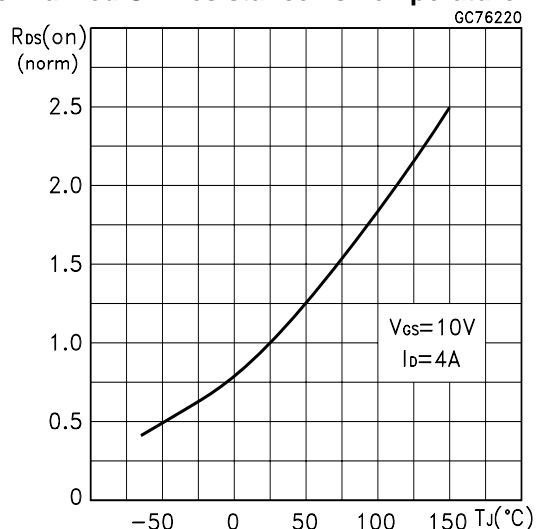
Capacitance Variations



Normalized Gate Threshold Voltage vs Temp.



Normalized On Resistance vs Temperature



Source-drain Diode Forward Characteristics

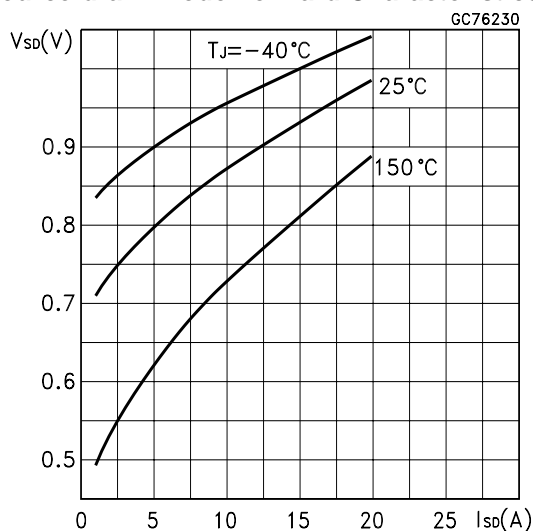


Fig. 1: Unclamped Inductive Load Test Circuit

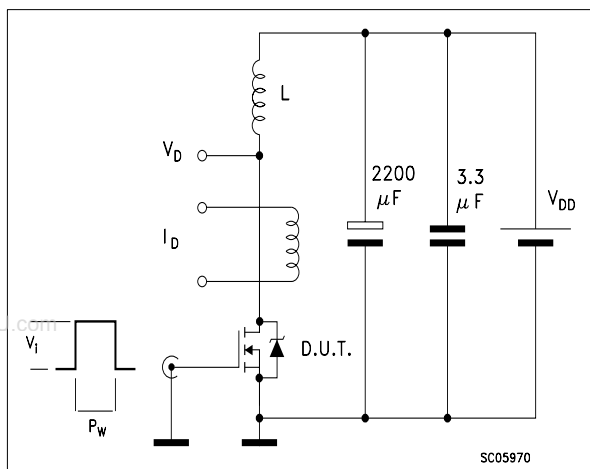


Fig. 2: Unclamped Inductive Waveform



Fig. 3: Switching Times Test Circuit For Resistive Load



Fig. 4: Gate Charge test Circuit

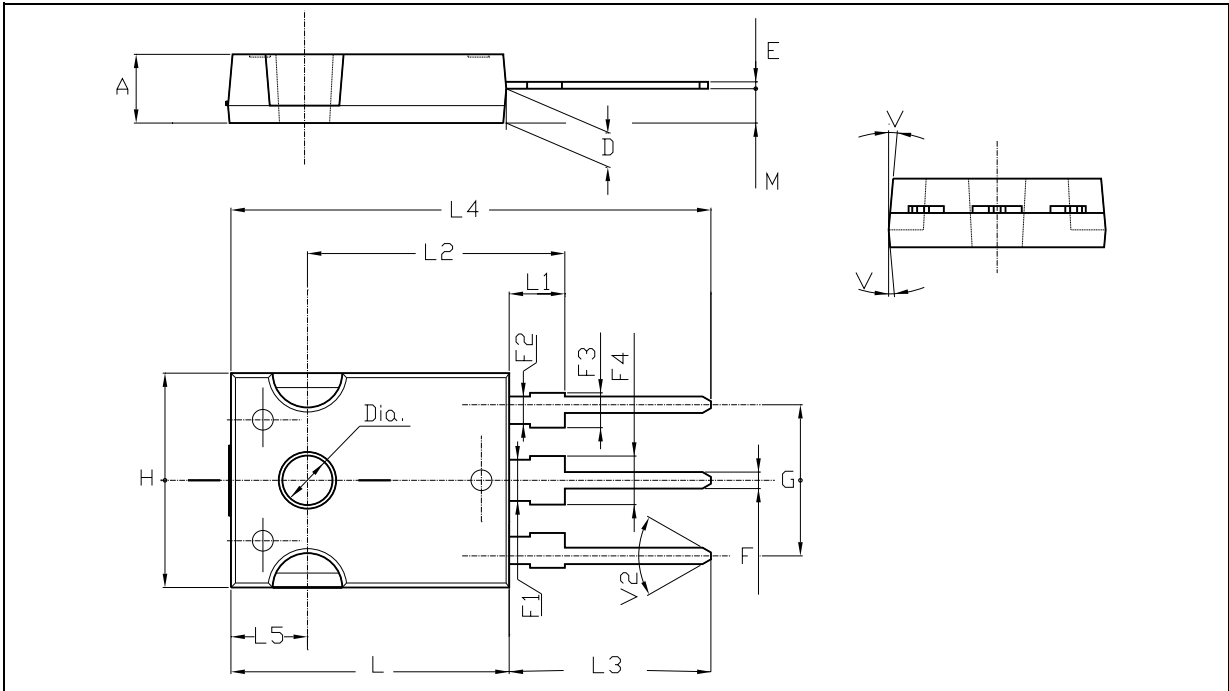


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



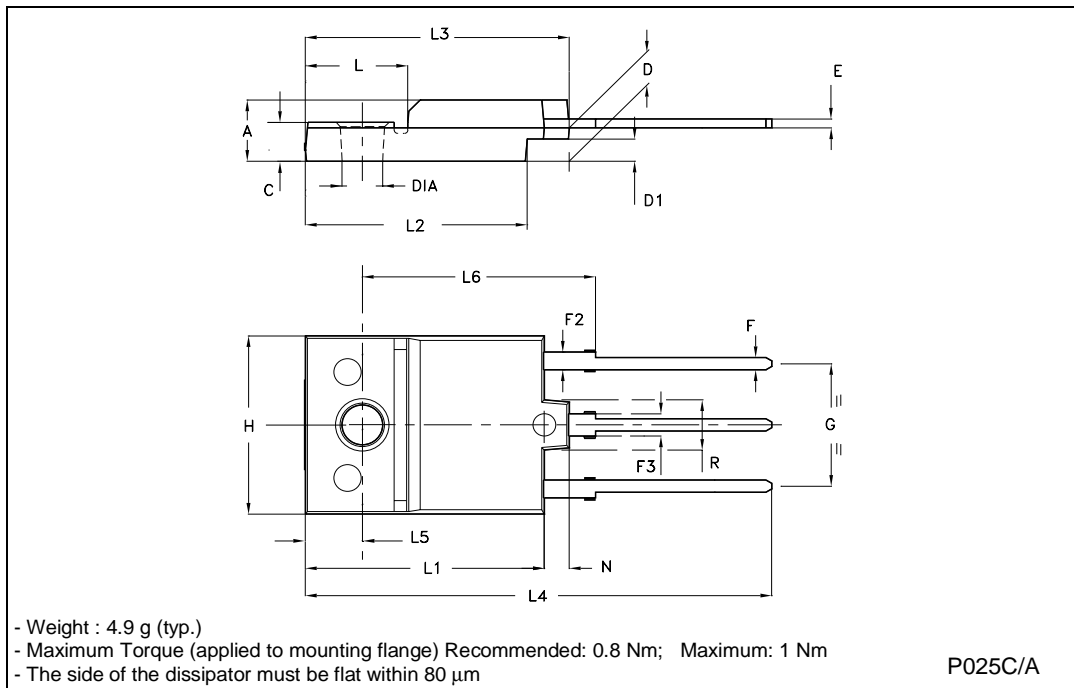
TO-247 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|------|-------|
| | MIN. | TYP | MAX. | MIN. | TYP. | MAX. |
| A | 4.85 | | 5.15 | 0.19 | | 0.20 |
| D | 2.20 | | 2.60 | 0.08 | | 0.10 |
| E | 0.40 | | 0.80 | 0.015 | | 0.03 |
| F | 1 | | 1.40 | 0.04 | | 0.05 |
| F1 | | 3 | | | 0.11 | |
| F2 | | 2 | | | 0.07 | |
| F3 | 2 | | 2.40 | 0.07 | | 0.09 |
| F4 | 3 | | 3.40 | 0.11 | | 0.13 |
| G | | 10.90 | | | 0.43 | |
| H | 15.45 | | 15.75 | 0.60 | | 0.62 |
| L | 19.85 | | 20.15 | 0.78 | | 0.79 |
| L1 | 3.70 | | 4.30 | 0.14 | | 0.17 |
| L2 | | 18.50 | | | 0.72 | |
| L3 | 14.20 | | 14.80 | 0.56 | | 0.58 |
| L4 | | 34.60 | | | 1.36 | |
| L5 | | 5.50 | | | 0.21 | |
| M | 2 | | 3 | 0.07 | | 0.11 |
| V | | 5° | | | 5° | |
| V2 | | 60° | | | 60° | |
| Dia | 3.55 | | 3.65 | 0.14 | | 0.143 |



ISOWATT218 MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|-------|------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 5.35 | | 5.65 | 0.211 | | 0.222 |
| C | 3.30 | | 3.80 | 0.130 | | 0.150 |
| D | 2.90 | | 3.10 | 0.114 | | 0.122 |
| D1 | 1.88 | | 2.08 | 0.074 | | 0.082 |
| E | 0.75 | | 0.95 | 0.030 | | 0.037 |
| F | 1.05 | | 1.25 | 0.041 | | 0.049 |
| F2 | 1.50 | | 1.70 | 0.059 | | 0.067 |
| F3 | 1.90 | | 2.10 | 0.075 | | 0.083 |
| G | 10.80 | | 11.20 | 0.425 | | 0.441 |
| H | 15.80 | | 16.20 | 0.622 | | 0.638 |
| L | | 9 | | | 0.354 | |
| L1 | 20.80 | | 21.20 | 0.819 | | 0.835 |
| L2 | 19.10 | | 19.90 | 0.752 | | 0.783 |
| L3 | 22.80 | | 23.60 | 0.898 | | 0.929 |
| L4 | 40.50 | | 42.50 | 1.594 | | 1.673 |
| L5 | 4.85 | | 5.25 | 0.191 | | 0.207 |
| L6 | 20.25 | | 20.75 | 0.797 | | 0.817 |
| N | 2.1 | | 2.3 | 0.083 | | 0.091 |
| R | | 4.6 | | | 0.181 | |
| DIA | 3.5 | | 3.7 | 0.138 | | 0.146 |



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